

Scanning Acoustic Microscope (CSAM)



Application

- Non-destructive Failure analysis tool
- Evaluation microelectronic components like ceramic chip capacitors (CSPs), die attach, chip scale packages, Ball grid arrays (BGAs), power modules etc.
 - Typical defects: Cracks, Opens, Bridging, Voiding
- Inspection of IC components & solder joints on printed circuit boards (PCBs) and Lead free devices

Features

Model:	Gen5
Manufacturer:	Sonoscan
Features:	<ul style="list-style-type: none"> • Locates hidden flaws before they lead to failures • Detects delamination as thin a 200 Angstroms • Isolates material property variations • Measures material density, porosity, inclusions, cracks and voids • Assesses thermal, impact and fatigue damage